

CLAIMS

1. (Amended) A transfer member comprising:
a substrate sheet (2, 52);
a mold release layer (3, 53) of a belt-shaped pattern laminated on the substrate sheet;
an ionizing radiation curing layer (4, 54) laminated all over a surface on the mold release layer;
a patterned layer (5, 55) laminated all over a surface or partially on the ionizing radiation curing layer;
and
an adhesive layer (6, 56) laminated on the patterned layer, so as not to locate at a region where the mold release layer is not formed, only partially in a portion where the adhesive layer overlaps with the mold release layer.
2. The transfer member as claimed in claim 1, wherein the adhesive layer is laminated in a region narrower along a direction of width of the transfer member than a region where the adhesive layer overlaps with the mold release layer.
3. (Twice Amended) A transfer member comprising:
a substrate sheet (2, 52);
a mold release layer (3, 53) of a belt-shaped pattern laminated on the substrate sheet;
an ionizing radiation curing layer (4, 54) laminated all over a surface on the mold release layer;
a patterned layer (5, 55) laminated all over a surface or partially on the ionizing radiation curing layer;
and
an adhesive layer (6, 56) laminated on the patterned layer, so as not to locate at a region where the mold release layer is not formed, only partially in a portion where the adhesive layer overlaps with the mold release layer,
wherein the substrate sheet is so constructed that the substrate sheet has a peel strength smaller than 50 N/m with respect to the resin board in a portion of the substrate sheet where the mold release layer is not provided when the transfer member is peeled off at an angle of 90° with respect to the resin

board after the transfer member is bonded to a resin board (144).

4. The transfer member as claimed in claim 1 or 2, further comprising: an anchor layer (7, 58) laminated wholly or partially between the ionizing radiation curing layer and the patterned layer.

5. The transfer member as claimed in claim 3, further comprising: an anchor layer (7, 58) laminated wholly or partially between the ionizing radiation curing layer and the patterned layer.

6. The transfer member as claimed in claim 1, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is wholly laminated at the portion where the adhesive layer overlaps with the mold release layer as well as the other portion on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.

7. The transfer member as claimed in claim 3, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is wholly laminated at the portion where the adhesive layer overlaps with the mold release layer as well as the other portion on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.

8. The transfer member as claimed in claim 4, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is wholly laminated at the portion where the adhesive layer overlaps with the mold release layer as well as the other portion on the patterned layer, and

the transfer member further comprises a nonadhesive

layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.

9. The transfer member as claimed in claim 5, wherein the patterned layer is laminated wholly or partially on the ionizing radiation curing layer, the adhesive layer is wholly laminated at the portion where the adhesive layer overlaps with the mold release layer as well as the other portion on the patterned layer, and

the transfer member further comprises a nonadhesive layer (57) laminated on the adhesive layer at least partially in a portion where the nonadhesive layer does not overlap with the mold release layer.